



Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model

[List multiple models if applicable.]

HP ENVY x360 15 Convertible PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm PCA	4
Batteries	All types including standard alkaline and lithium coin or button style batteries Battery pack;RTC	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries N/A	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps 1	LED
Cathode Ray Tubes (CRT)	N/A	0
Capacitors / condensers (Containing PCB/PCT)	N/A	0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	N/A	0
External electrical cables and cords	N/A	0
Gas Discharge Lamps	N/A	0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	N/A	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations. N/A	0
Components and waste containing asbestos	N/A	0
Components, parts and materials containing refractory ceramic fibers	N/A	0

Components, parts and materials containing radioactive substances	N/A	0
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2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Phillips screwdriver (for 8 PCS on bottom case)	#1 2.5~3.0 kg-cm
Description #2 Phillips screwdriver (for 5 PCS on motherboard)	#1 2.5~3.0 kg-cm
Description #3 Phillips screwdriver (for 5 PCS on Battery)	#1 2.5~3.0 kg-cm
Description #4 Phillips screwdriver (for 7 PCS on base side hinge bracket)	#1 2.5~3.0 kg-cm
Description #5 Use jig disassembly Lcd Bezel with Lcd cover	Pick thickness 0.3~0.4mm

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

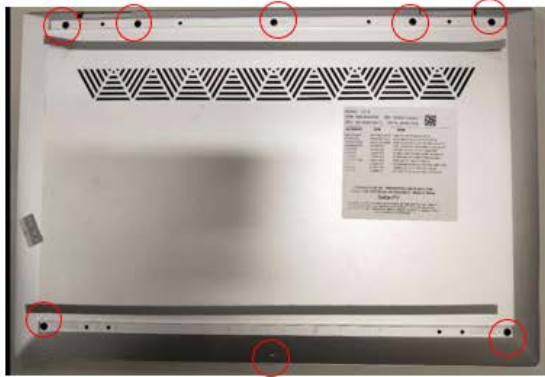
1. Remove rear side rubber foot refer figure 1
2. Release 7pcs Phillips screw from bottom case refer figure 2
3. Two hand together disassemble bottom case from arrow side refer figure 3
4. Release 6pcs Phillips screw from Battery refer figure 4
5. Disassemble:DC-in cable 、 WLAN cable 、 CCD cable 、 EDP cable 、 SPK cable 、 SD FFC 、 HDD FFC 、 KB BL FPC 、 KB FPC 、 TP FFC refer figure 5
6. Release 13pcs Phillips screw from PCB, Next Teardown Mainboard and SD board and USB board refer figure 6
7. Release 4pcs Phillips screw from left side hinge bracket refer figure 7
8. Release 3pcs Phillips screw from right side hinge bracket refer figure 8
9. Disassemble LCD module initial step pick insert gap between LCD Cover and LCD Bezel refer figure 9
10. Release 6pcs Phillips screw from right & left hinge Bracket refer figure 10

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



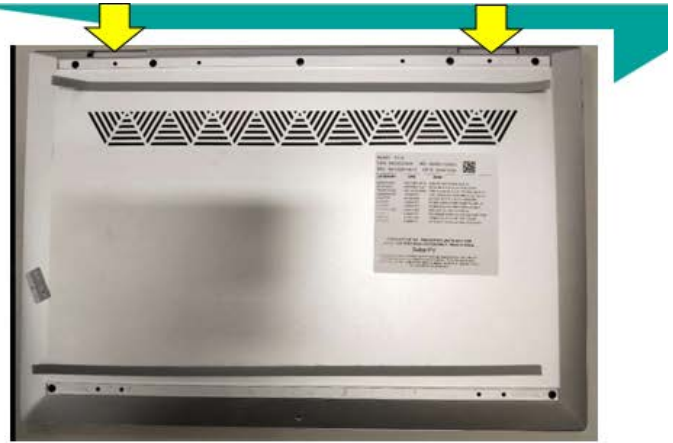
1. Remove 2pcs of rubber foot.

Figure 1



1. Loosen 8pcs Phillips screw and 1pc hexalobular socket screw

Figure 2



1. Separate L-case and U-case by two hands.

Figure 3



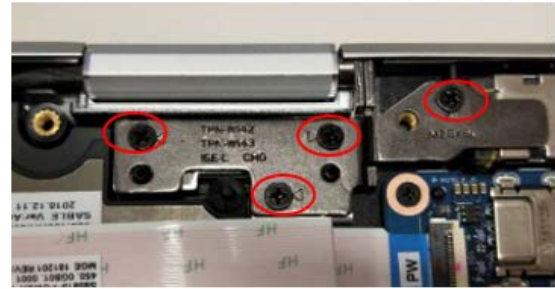
1. Loosen 5pcs Phillips screw and take the battery away from U-case.

Figure 4



1. Disassembly: DC-IN cable, WLAN cable, CCD cable, EDP cable, SPK cable, SD DB cable, USB DB cable, KB FPC, KB BL FPC, TP FFC, FP FPC.

Figure 5



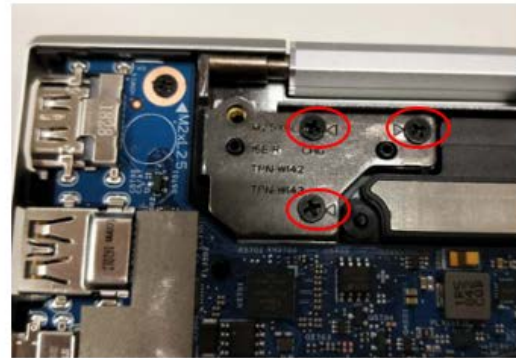
1. Loosen 4pcs phillips screw from left-side hinge.

Figure 7



1. Loosen 5 pcs phillips screw.
2. Take main board, SD DB and USB DB and switch DB away from U-case

Figure 6



1. Loosen 3pcs phillips screw from right-side hinge.

Figure 8



1. Use a pick to insert the gap between A-cover and Bezel for disassembly.

Figure 9



1. Loosen 6pcs phillips screw from both sides hinge bracket.

Figure 10